



PK730 (v1.0) May 29, 2015

# 100% Material Declaration Data Sheet Spartan®-6 Cu Wire CSG484 Package

**Average Weight: 1.286 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.053052</b>	<b>4.125%</b>
	Silicon	7440-21-3	100.00	Main material	0.053052	
<b>Die Attach Material</b>					<b>0.016016</b>	<b>1.245%</b>
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
<b>Copper Wire</b>					<b>0.003919</b>	<b>0.305%</b>
	Cu	7440-50-8	98.25	Main material	0.003850	
	Pd	7440-05-3	1.75	Dopant	0.000069	
<b>Mold Compound</b>					<b>0.449393</b>	<b>34.945%</b>
	Epoxy Resin	Trade secret	7.50	Main material	0.033704	
	Phenol Resin A	9003-35-4	3.00	Main material	0.013482	
	Phenol Resin B	Trade secret	3.00	Main material	0.013482	
	Silica(Amorphous) A	60676-86-0	67.95	Filler	0.305363	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.067409	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.013482	
Carbon black	1333-86-4	0.55	Color agent	0.002472		
<b>Solder Balls</b>					<b>0.170571</b>	<b>13.264%</b>
	Tin (Sn)	7440-31-5	96.50	Main material	0.164601	
	Silver (Ag)	7440-22-4	3.00	Main material	0.005117	
	Copper (Cu)	7440-50-8	0.50	Main material	0.000853	

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Substrate					<b>0.593049</b>	<b>46.116%</b>
	Au	7440-57-5	0.15	Main material	0.000902	
	Ni	7440-02-0	1.40	Main material	0.008316	
	Cu foil	7440-50-8	31.33	Main material	0.185775	
	Cu plating	7440-50-8	5.16	Plating	0.030581	
	Continuous Filament Fiber Glass	65997-17-3	21.04	Glass Fiber	0.124772	
	BT Core	NA 7440-50-8	21.76	Core	0.129051	
	Solder Mask	7727-43-7 7631-86-9 34590-94-8 14807-96-6 85954-11-6 91-20-3 NA	4.47	Solder mask	0.026509	
	Prepregs	NA	14.69	Prepregs	0.087142	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

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